

Amendments to the Specification:

Please replace the paragraph beginning at page 8, line 11 with the following amended paragraph:

The two wafers 7, 8 are placed with their surfaces one on top of the other and directly connected to one another by means of eutectic bonding. In accordance with FIG. 3, the two wafers 7, 8 here in each case have a metallization ~~[[12']]~~ 11', 21'. One metallization is preferably a gold metallization ~~[[12']]~~ 11', and the other metallization is preferably a gold-tin metallization 21'. Furthermore, trenches or cutouts 9 are provided in the surface of at least one wafer. The cutouts 9 ensure that a connection between the two wafers is effected only in defined regions. Alignment aids (so-called fiducials) are also provided (not illustrated) on the wafers 7, 8. The eutectic bonding of the two wafers is effected in a manner known per se.